

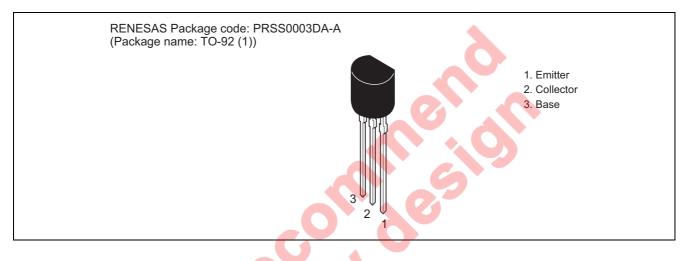
Silicon PNP Epitaxial

REJ03G0639-0300 (Previous ADE-208-1011A) Rev.3.00 Aug.10.2005

## Application

Low frequency amplifier

## Outline



## Absolute Maximum Ratings

(Ta	- 2	5°C)
v i a	- <i>L</i> .	., .,

			(1a - 23C)
Item	Symbol	Rating	Unit
Collector to base voltage	V <sub>CBO</sub>	-90	V
Collector to emitter voltage	V <sub>CEO</sub>	-90	V
Emitter to base voltage	V <sub>EBO</sub>	-5	V
Collector current	Ι <sub>C</sub>	-100	mA
Emitter current	Ι <sub>Ε</sub>	100	mA
Collector power dissipation	Pc	400	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C



## **Electrical Characteristics**

						(Ta = 25°C)
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	V <sub>(BR)CBO</sub>	-90	—	—	V	$I_{C} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	V <sub>(BR)CEO</sub>	-90	—	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	V <sub>(BR)EBO</sub>	-5	—	_	V	$I_E = -10 \ \mu A, \ I_C = 0$
Collector cutoff current	I <sub>CBO</sub>	_	—	-0.1	μA	$V_{CB} = -70 \text{ V}, I_E = 0$
Emitter cutoff current	I <sub>EBO</sub>	—	—	-0.1	μA	$V_{EB} = -2 V, I_C = 0$
DC current trnsfer ratio	h <sub>FE</sub> * <sup>1</sup>	250	—	800		$V_{CE} = -12 V$ ,
						$I_{\rm C} = -2 {\rm mA}^{*2}$
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	—	-0.05	-0.15		$I_{\rm C} = -10  {\rm mA}_{\rm c}$
						$I_{\rm B} = -1  {\rm mA}^{*2}$
Base to emitter saturation voltage	V <sub>BE(sat)</sub>	_	-0.7	-1.0	V	
Gain bandwidth product	f <sub>T</sub>	—	130	_	MHz	$V_{CE} = -6 V,$
						$I_{\rm C} = -10 \text{ mA}$
Collector output capacitance	Cob	—	3.2	—	pF	$V_{CB} = -10 \text{ V}, I_E = 0,$
						f = 1 MHz

Notes: 1. The 2SA1188 is grouped by  $h_{FE}$  as follows.

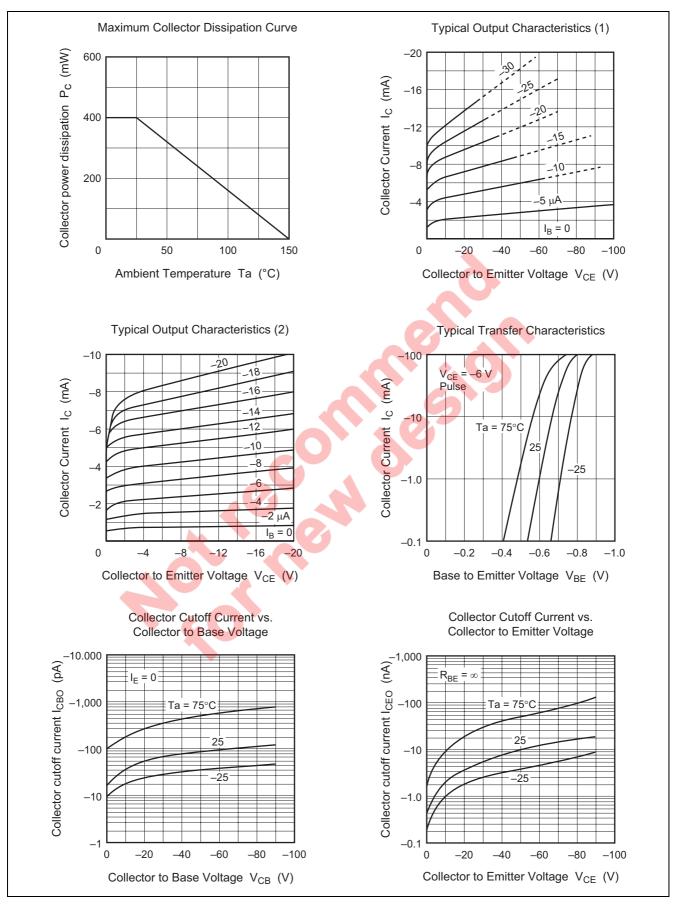
2. 1	Julse test
D	E

250 to 500 400 to 800

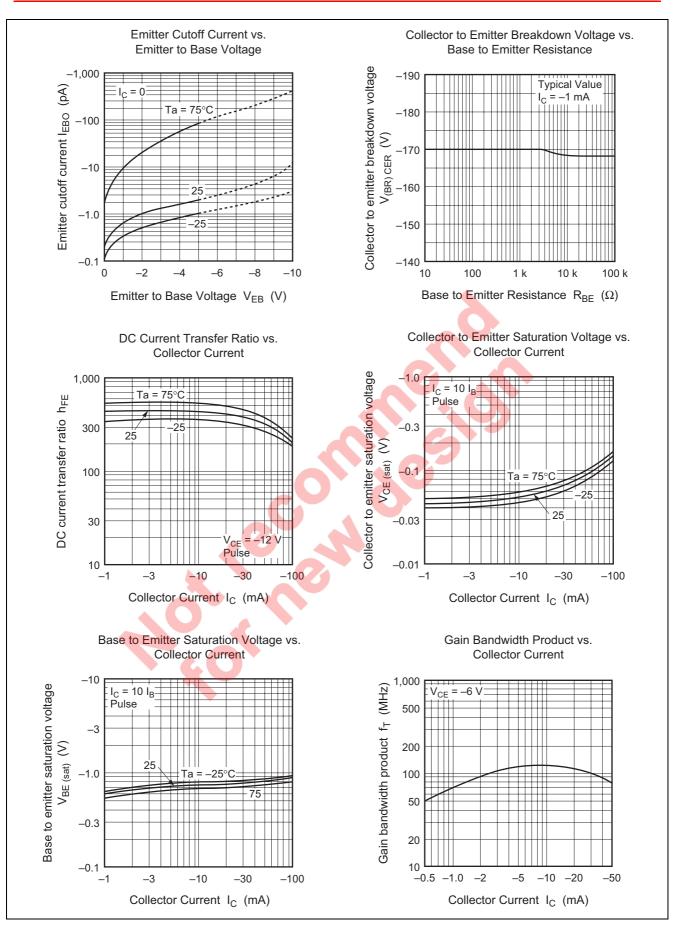
Rev.3.00 Aug 10, 2005 page 2 of 6



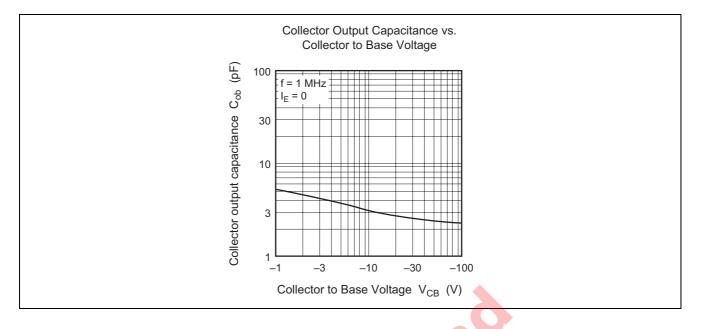
## **Main Characteristics**





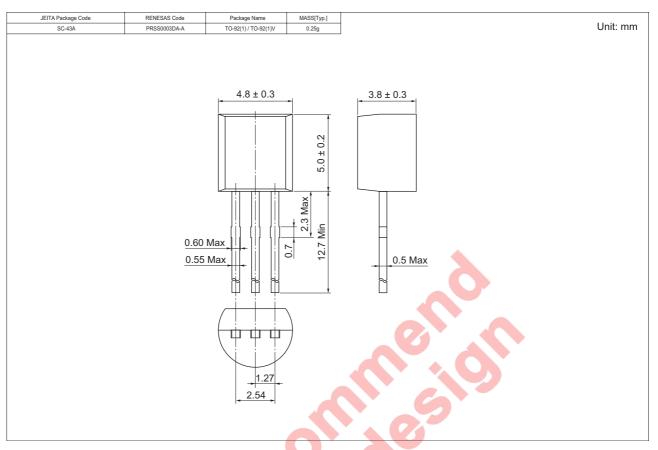








# Package Dimensions



## **Ordering Information**

Part Name	Quantity		Shipping Container
2SA1188DTZ-E	2500	H	Hold Box, Radial Taping
2SA1188ETZ-E			

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



# Renesas Technology Corp. sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs! 1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

## Notes regarding these materials

- Notes regarding these materials
   These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
   Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
   All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. virbut notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
   The information described here may contain technical inaccuracies or typographical errors. Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors. Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (http://www.renesas.com).
   When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to any sing any or all of the information contained in these materials.

- Nome page (ntp://www.renesas.com).
  4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
  5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- use. 6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials. 7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination. Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited. 8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



## **RENESAS SALES OFFICES**

Refer to "http://www.renesas.com/en/network" for the latest and detailed information.

http://www.renesas.com

Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd. 7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

## Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd. Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

## Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510